

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	("6515826") or ("6242320").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/27 14:28
S2	1	"10553470".rlan. or ("10".src. and "553470".ap.)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/04/27 14:48
S3	2	("6156621").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/29 10:05
S4	6	("6156621") or ("6242320") or ("6514858").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/29 10:08
S5	2	("6515826").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/29 10:14
S7	565	(trench recess hole groove) same test same thick\$4 same (polish\$3 CMP)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/29 11:22
S6	27605	(trench recess hole groove) and test and thick \$4 and (polish\$3 CMP)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/29 11:22
S8	355	(monitor\$3 detect\$3) and S7	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/29 11:24
S9	135	S8 and @ad<"20040416"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/04/29 11:33

S10	22	("4318148" "4416056" "5113300" "5643824" "5734534" "5814547" "5827437" "5872693" "6191916" "6191918" "6204997" "6246541" "6304414" "6320726"). PN. OR ("6515826"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/29 11:48
S11	2	("6809031").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/30 12:36
S12	2	("20080085569").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/30 12:37
S13	2	("7333370").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/30 12:38
S15	31	("20020088769" "20020097405" "20020146867" "20060292825" "6057171" "6071822" "6127237" "6275297" "6291254" "6306755" "6312963" "6342401" "6396076" "6403389" "6770213" "6821865" "6849521").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/30 12:45
S16	14	((RALF) near2 (LERNER)). INV.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/30 12:48
S19	8	((("6403389") or ("2002088769") or ("6306755")).PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/30 12:50
S20	130	(x-fab near semiconductor). as.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/30 12:51
S21	71	trench same ("SiO. sub 2" (silicon near dioxide)) same ((different varying) with width)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/30 13:58

S22	2	("6156621").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/30 14:53
S25	963	(S23 S24) and (trench with etch\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/30 15:58
S24	1144	(438/693).CCLS.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/30 15:58
S23	3241	(438/692).CCLS.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/30 15:58
S28	161	S25 and S27	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/30 16:00
S27	1412545	(detect\$3 monitor\$3 measur\$3) same (optical \$3 laser light)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/30 16:00
S30	1	"11441125".rlan. or ("11". src. and "441125".ap.)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/05/01 09:01
L1	545	(438/7).CCLS.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/21 10:37
L2	134	1 and (trench groove)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/21 10:39
L3	4	((("6960416") or ("6858361"))).PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/21 10:40
L4	2	("20030228532").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/21 10:41

L7	631	(430/316).CCLS.	US-PGPUB; USPAT; FPRS; EPO: JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/21 10:51
L5	3065	(430/30).CCLS.	US-PGPUB; USPAT; FPRS; EPO: JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/21 10:51
L8	220	(156/345.25).CCLS.	US-PGPUB; USPAT; FPRS; EPO: JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/21 10:52
L9	602	(216/60).CCLS.	US-PGPUB; USPAT; FPRS; EPO: JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/21 10:53
L11	6101	1 5 7 8 9 10	US-PGPUB; USPAT; FPRS; EPO: JPO; DERWENT; IBM_TDB	OR	ON	2009/05/21 10:54
L10	1451	(438/16).CCLS.	US-PGPUB; USPAT; FPRS; EPO: JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/21 10:54
L14	319	13 and @ad<"20040416"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/05/21 10:55
L13	451	depth and 12	US-PGPUB; USPAT; FPRS; EPO: JPO; DERWENT; IBM_TDB	OR	ON	2009/05/21 10:55
L12	1022	(CMP polish\$3 (chemical near mechanical near polish\$3)) and 11	US-PGPUB; USPAT; FPRS; EPO: JPO; DERWENT; IBM_TDB	OR	ON	2009/05/21 10:55
L15	6	(test and trenches and (depth shallow\$2 deep\$2) and (remov\$3 etch\$3 polish \$3) and monitor\$3 and detect\$3).clm.	US-PGPUB; USPAT; FPRS; EPO: JPO; DERWENT; IBM_TDB	OR	ON	2009/05/21 12:27
L16	3	("5637186" "5903011" "6768324").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/05/21 12:30
L17	1729	5 and @ad<"20040416"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/05/21 12:32

L19	137	18 and trench	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/05/21 12:33
L18	1309	17 and semiconductor	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/05/21 12:33

5/21/2009 12:45:36 PM

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